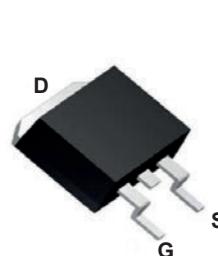
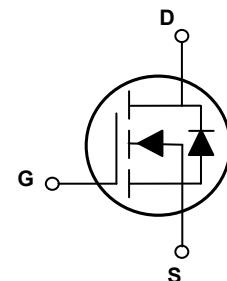


## Main Product Characteristics

$V_{(BR)DSS}$	85V
$R_{DS(ON)}$	5.5mΩ (Max.)
$I_D$	120A



TO-263



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSGT5R585 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	85	V
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, @ Steady-State ( $T_A=25^\circ\text{C}$ ) <sup>1</sup>	$I_D$	120	A
Continuous Drain Current, @ Steady-State ( $T_A=100^\circ\text{C}$ )		90	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	480	A
Power Dissipation ( $T_A=25^\circ\text{C}$ )	$P_D$	160	W
Linear Derating Factor ( $T_A=25^\circ\text{C}$ )		1.28	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	400	mJ
Junction-to-Case	$R_{\theta JC}$	0.78	$^\circ\text{C}/\text{W}$
Junction-to-Ambient (PCB Mounted, Steady-State) <sup>4</sup>	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	$T_J/T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	85	92.5	-	V
Drain-to-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=85\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
		$T_J=125^\circ\text{C}$	-	-	50	
Gate-to-Source Forward Leakage	$I_{\text{GSS}}$	$V_{\text{GS}}=20\text{V}$	-	-	100	$\text{nA}$
		$V_{\text{GS}}=-20\text{V}$	-	-	-100	
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_D=50\text{A}$	-	4.2	5.5	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	2.2	3	3.9	V
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=40\text{V}$ $f=1\text{MHz}$	-	4284	-	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	668	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	18	-	
Total Gate Charge	$Q_g$	$I_D=50\text{A}, V_{\text{DS}}=40\text{V},$ $V_{\text{GS}}=10\text{V}$	-	69	-	$\text{nC}$
Gate-to-Source Charge	$Q_{\text{gs}}$		-	30	-	
Gate-to-Drain ("Miller") Charge	$Q_{\text{gd}}$		-	16	-	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=40\text{V},$ $R_{\text{GEN}}=24\Omega, I_D=13.2\text{A}$	-	59	-	$\text{nS}$
Rise Time	$t_r$		-	82	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	126	-	
Fall Time	$t_f$		-	72	-	
Gate Resistance	$R_g$	$f=1\text{MHz}$	-	1.7	-	$\Omega$
<b>Source-Drain Ratings and Characteristics</b>						
Continuous Source Current (Body Diode)	$I_s$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	120	A
Pulsed Source Current (Body Diode)	$I_{\text{SM}}$		-	-	480	A
Diode Forward Voltage	$V_{\text{SD}}$	$I_s=50\text{A}, V_{\text{GS}}=0\text{V}$	-	1	1.2	V
Reverse Recovery Time	$T_{\text{rr}}$	$T_J=25^\circ\text{C}, I_F=20\text{A},$ $dI/dt=100\text{A}/\mu\text{s}$	-	53	-	$\text{nS}$
Reverse Recovery Charge	$Q_{\text{rr}}$		-	0.31	-	

Note:

1. Pulse test: pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
2. Repetitive rating; pulse width limited by max. junction temperature.
3.  $L=0.5\text{mH}, I_{\text{AS}}=40\text{A}, V_{\text{DD}}=72\text{V}, T_J=25^\circ\text{C}$ .
4. Device mounted on FR-4 PCB, 1inch x 0.85inch x 0.062inch.

## Typical Electrical and Thermal Characteristic Curves

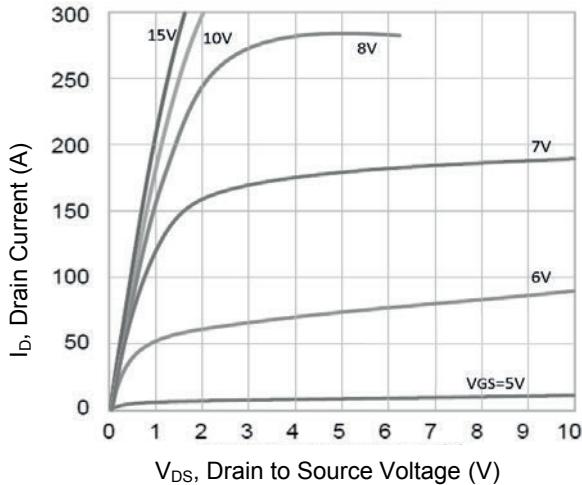


Figure 1. Typical Output Characteristics

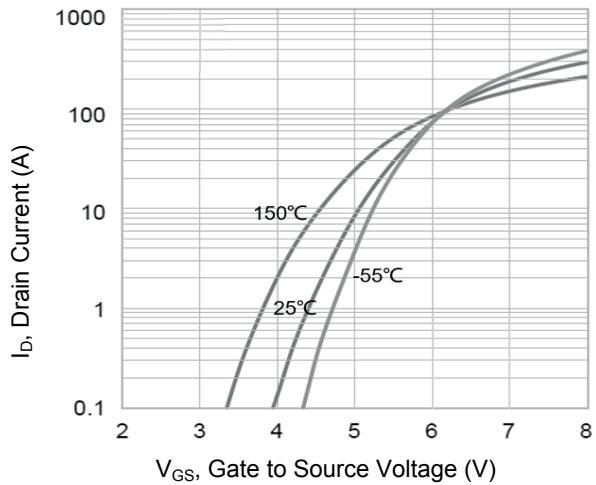


Figure 2. Transfer Characteristics

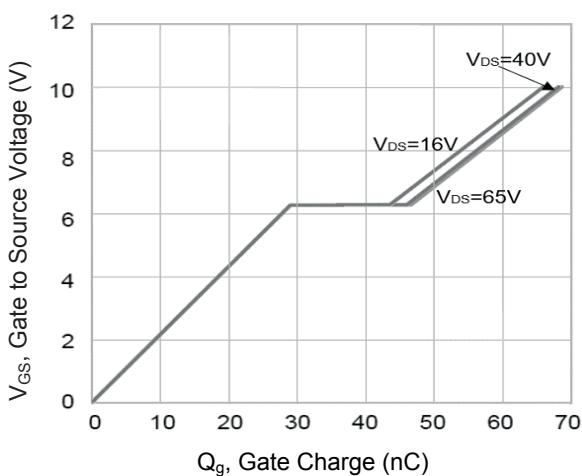


Figure 3. Gate Charge

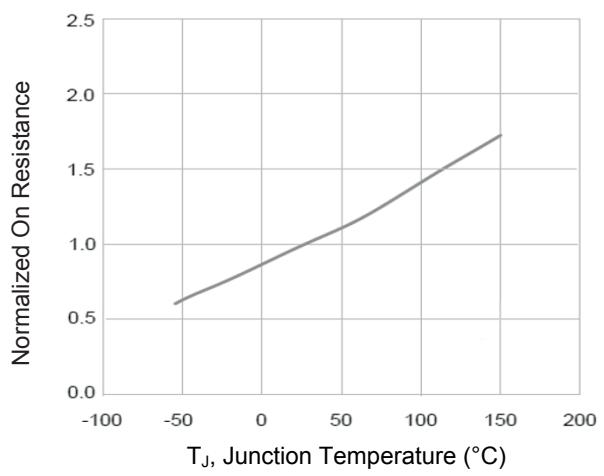


Figure 4. Normalized  $R_{DS(ON)}$  Vs.  $T_J$

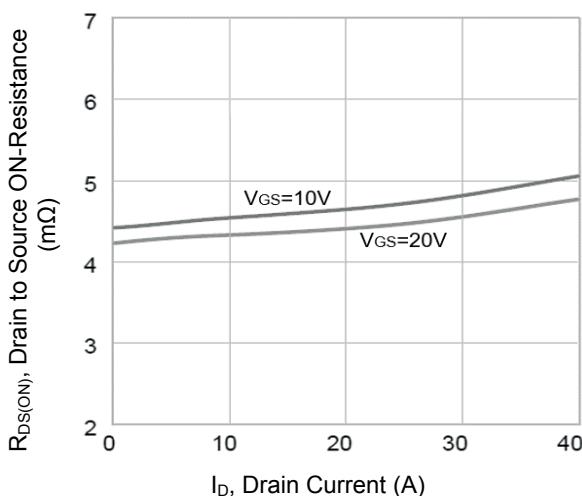


Figure 5. Drain-Source On-Resistance

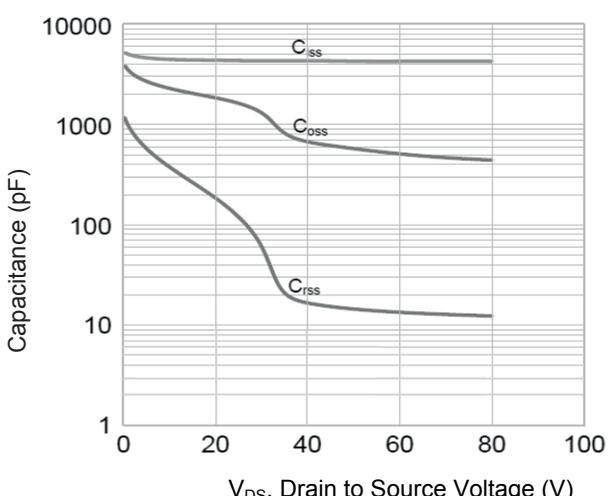


Figure 6. Typical Capacitance Vs. Drain to Source Voltage

## Typical Electrical and Thermal Characteristic Curves

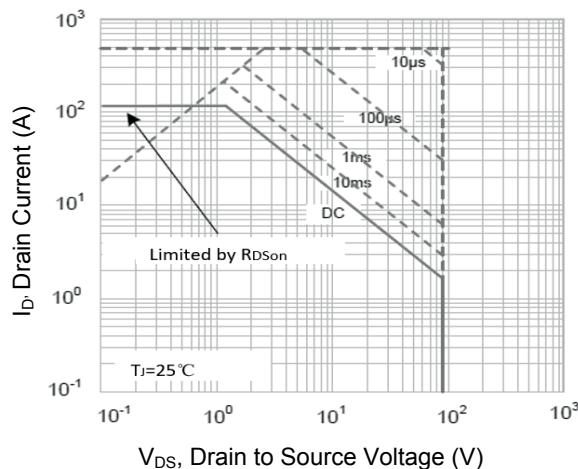


Figure 7. Safe Operation Area

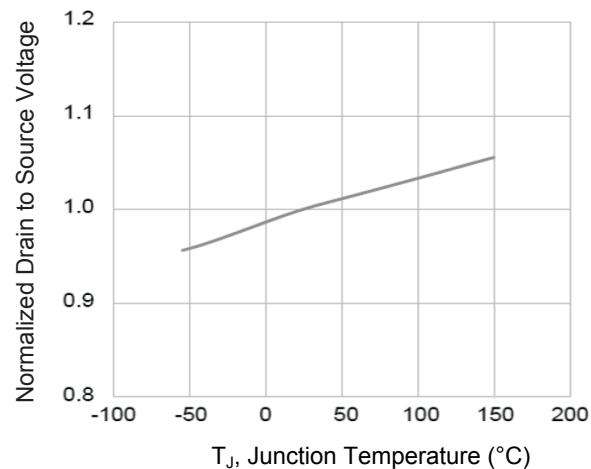
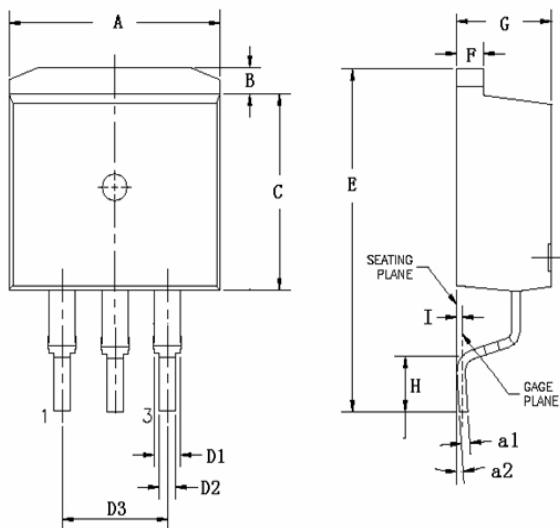


Figure 8. Normalized  $\text{BV}_{\text{ds}}$  Vs.  $T_J$

**Package Outline Dimensions TO-263(D2PAK)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	9.66	10.28	0.380	0.405
B	1.02	1.32	0.040	0.052
C	8.59	9.40	0.339	0.370
D1	1.14	1.40	0.045	0.055
D2	0.70	0.90	0.028	0.037
D3	5.08 TYP.		0.200 TYP.	
E	15.09	15.39	0.594	0.606
F	1.15	1.40	0.045	0.055
I	0.25 TYP.		0.010 TYP.	
G	4.30	4.70	0.169	0.185
H	2.29	2.79	0.090	0.110
K	1.30	1.60	0.051	0.063
a1	0.45	0.65	0.018	0.026
a2	0°	8°	0°	8°